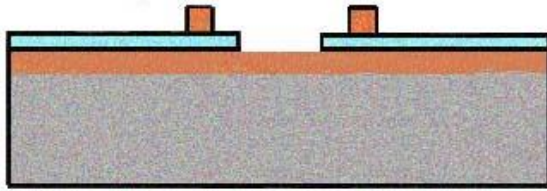


**FASTHERM® TECHNOLOGY
BASE BIMETAL Cu/Al**



- ALUMINIO / ALUMINIUM
- PREPREG TERMICO / THERMAL PREPREG
- COBRE / COPPER

*Espesor/Thickness Base Material: Al 0.93 - 1.43mm
Cu 100µm*

Espesor/Thickness Dielectric: 25 µm

Espesor/Thickness Cu: 35 - 70 - 105µm

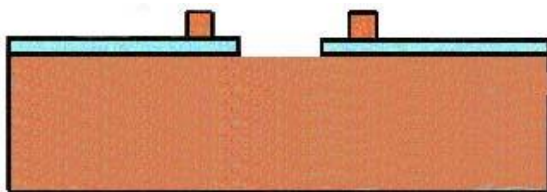
Taladro minimo/Min drill: 1mm

Anchura conductor min/Min conductor width: 0.15mm

Espacio conductor min/Min conductor space: 0.15mm

Corona minima/Min annular ring: 0.18mm

**FASTHERM® TECHNOLOGY
BASE Cu**



- PREPREG TERMICO / THERMAL PREPREG
- COBRE / COPPER

Espesor/Thickness Cu Base: 0.4 -1 - 1.5 - 2mm

Espesor/Thickness Dielectric: 25 µm

Espesor/Thickness Cu: 35 - 70 - 105 µm

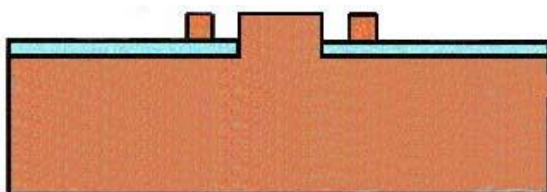
Taladro minimo/Min drill: 1mm

Anchura conductor min/Min conductor width: 0.15mm

Espacio conductor min/Min conductor space: 0.15mm

Corona minima/Min annular ring: 0.18mm

**DIRECTHERM TECHNOLOGY
BASE Cu**



- PREPREG TERMICO / THERMAL PREPREG
- COBRE / COPPER

Espesor/Thickness Cu Base: 0.4 -1 - 1.5 - 2mm

Espesor/Thickness Dielectric: 125 µm

Espesor/Thickness Cu: 35 - 70 - 105 µm

Taladro minimo/Min drill: 1mm

Min Thermal pad: 0.6x1.4mm

Max Thermal pad: 5x5mm

Espacio Thermal pad/Space Thermal pad: 1mm min

Anchura conductor min/Min conductor width: 0.15mm

Espacio conductor min/Min conductor space: 0.15mm

Corona minima/Min annular ring: 0.18mm